

We thank you for your price request and are pleased to present you the following quotation today

21 October 2015

Administrative details

Your references

Offer nr.	B0513227	Purchase reference	CIT PO: 271337
Service	STANDARD pool	(separate PO for STENCIL)	-
Board name	n-DAP	Project reference	-
		Article number	-

Invoicing & delivery details

Invoice to:

Cork Institute of Technology
Catherine Cunningham
Rossa Avenue Bishopstown
ACCOUNTS PAYABLE
co Cork
Ireland
+353 (21) 4326584
Catherine.Cunningham@cit.ie

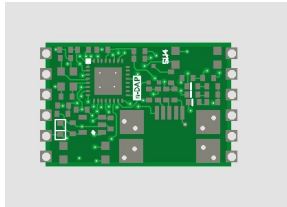
Delivered to:

Cork Institute of Technology, NIMBUS
CENTRE
Nikolaos Chalikias
Rossa Avenue Bishopstown
co Cork
Ireland
+353 (21) 4335479
nikolaos.chalikias@cit.ie

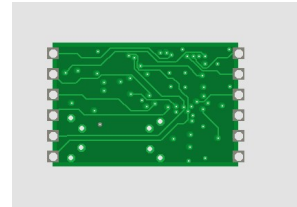
PCB Visualizer

PCB images

Top view :



Bottom view:



Buildup & Mechanical plan

Board buildup :

	Top copper - CopperFoil - 0.018mm
	Prepreg - PR7628 - 0.18mm
	Prepreg - PR7628 - 0.18mm
	Inner copper 1 - 0.035mm
	Core - FR4-Improved - 0.71mm
	Inner copper 2 - 0.035mm
	Prepreg - PR7628 - 0.18mm
	Prepreg - PR7628 - 0.18mm
	Bottom copper - CopperFoil - 0.018mm

Technology & options

Board definition

Number of layers	4	Delivery format	No
PCB width (X)	22.86 mm	PCB height (Y)	15.25 mm
eC-registration compatible	No		

Board definition

Top soldermask	Green	Bottom soldermask	Green
Top legend	White	Bottom legend	No
Surface finish	Any lead free finish		
Bare board testing	Yes		

Board technology

Pattern class	6	Drill class	Drill C
Outer layer trackwidth (OL-TW)	0.150 mm	Hole density	< 1000/dm2
Outer layer isolation distance (OL-TT-TP-PP)	0.150 mm	Holes <= may be reduced	0.45 mm
Outer layer annular ring (OAR)	0.125 mm		
Inner layer trackwidth (IL-TW)	0.150 mm	Holes <= may be reduced	0.45 mm
Inner layer isolation distance (IL-TT-TP-PP)	0.150 mm		
Inner layer annular ring (IAR)	0.125 mm		

Material definition

Board thickness	1.55 mm	Board buildup	Standard buildup
Base material	FR4IMP	Material Tg	145-150°C
Outer layer copper foil	18µm(End-Cu +/-35µm)	Inner layer copper foil	35µm
Extra PTH runs	0	Extra press cycles	0
Reversed buildup	No	Inner layer core thickness	Standard

Stencils

Top stencil	Yes	Bottom stencil	No
Stencil width (X)	62.86 mm	Stencil width (X)	62.86 mm
Stencil height (Y)	55.25 mm	Stencil height (Y)	55.25 mm
eC-registration compatible	No		

Advanced options

Copper up to board edge	No	Plated holes on the board edge	Yes
Specific tolerances	No	Specific marking	No
Press-fit holes	No	Depth routing	No
Round-edge plating	No	Chamfered mechanical holes	No

Pricing**Printed circuits**

Basket nr.	Delivery term	Quantity	Unit price	Transport price	Transport mode	Total price	VAT	Gross
B0513227	7 Working days	20	6.50 EUR	3.68 EUR	Express	133.72 EUR	0.0 %	133.72 EUR

Stencils

Basket nr.	Stencil type	Delivery term	Quantity	Unit price	Transport price	Transport mode	Total price	VAT	Gross
B0513227	Stencil-Top	7 Working days	1	31.74 EUR	0.00 EUR	Express	31.74 EUR	0.0 %	31.74 EUR

Payment terms & conditions

The payment term is 30 days from invoice date.

This quotation is valid for 30 days. All our deliveries are according to our general terms and conditions of delivery. These are available on the website , and agreed upon between us during the registration procedure. All above mentioned prices are an indication on the basis of the information at our disposal on the moment of quotation. These prices may be reviewed at the moment of order on the basis of the final documentation and conditions. The final quantity to be delivered can vary up to 5% of the ordered quantity. Delivery terms start counting upon receipt of the complete documentation and firm order.

EUROCIRCUITS N.V.
Antwerpsesteenweg 66
2800 MECHELEN
Belgium

www.eurocircuits.com

Phone: +3215281630
Fax: +32 15 28 16 31
E-mail: euro@eurocircuits.com